

8755 W. Higgins Road Suite 500 Chicago, Illinois USA 60631

April 11th, 2022

RE: PCN # ESU270-78 - SM24CANB-02HTG additional backend location approval

To our valued customers,

Littelfuse would like to notify you of an additional approved backend location for SM24CANB-02HTG TVS Diode Array (SPA® Diodes) product. This additional packaging supplier is necessary to provide stability, in response to the resurgence of the pandemic in Southeast Asia. This additional backend factory, located in China is fully approved for all assembly, test, and packing operation. This factory currently supports commercial and automotive products in the same packages.

Qualification efforts are completed, and the new factory is online for immediate shipments. Please see the documentation in the following pages for change details.

The affected product has been fully qualified in accordance with established performance and reliability criteria. The attached pages summarize the qualification results. Full qualification data and/or samples will be available upon request.

Form, fit, function changes: Nominal differences in package height

Part number changes: None

Effective date: July 11th, 2022 or sooner

Replacement products: N/A

Last time buy: N/A

This notification is for your information and acknowledgement. If you have any other questions or concerns, please contact Sophia Hu, Assistant Product Manager.

We value your business and look forward to assisting you whenever possible.

Best Regards,

Sophia Hu TVS Diode Array Assistant Product Manager Semiconductor Business Unit, Wuxi, China +86 510 85277701 - 7653 shu@littelfuse.com

PCN#:	Contact Information					
ESU270-78 Date: April 11 th , 2022	Name: Sophia Hu					
Product Identification :	Title: Assistant Product Manager					
SM24CANB-02HTG additional backend location	Phone #: +86 13771377277					
Implementation Date for Change:	Fax#: N/A					
July 11 th , 2022 or sooner	E-mail: shu@littelfuse.com					
<u> </u>	cription of Change:					
	ove additional backend assembly, test, and packing location for					
11	SM24CANB-02HTG.					
☐ Technology						
☐ Discontinuance/Obsolescence						
☐ Equipment						
□ Raw Material						
☐ Testing						
☐ Fabrication Process						
Other:						
Important Dates:						
□ Qualification Samples Available: Upon request □ Last Time Buy:						
☐ Final Qualification Data Available: Upon request						
☐ Date of Final Product Shipment:						
Method of Distinguishing Changed Product						
☐ Date Code,						
Other,						
Demonstrated or Anticipated Impact on Form, Fit, Function or Reliability:						
N/A						
LF Qualification Plan/Results:						
Yes						
Customer Acknowledgement of Receipt: Littelfuse requests you acknowledge receipt of this PCN. In your acknowledgement, you can						
grant approval or request additional information. Littelfuse will assume the change is acceptable if no acknowledgement is received within 30 days						
of this notice. Lack of any additional response within 90 days of PCN issuance further constitutes acceptance of the change.						



Prepared By: Jordan Hsieh-Product Engineering Manager,

Raider Chen-Product Engineer, Sophia Hu- Assistant Product Manager

Date : 2022/3/29

Device: SM24CANB-02HTG

Revision : A

1.0 Objective:

The purpose of this document is to qualify an additional assembly supplier for SM24CANB-02HTG. Summarize the physical, electrical and reliability test performed in qualification lots.

2.0 Applicable Devices:

2.1 Product name: SM24CANB-02HTG

3.0 Assembly, Process & Material Differences/Changes:

3.1 Assembly Changes

No change of assemble process.

3.2 Process Changes

No change of process method.

3.3 Material Change

SM24CANB-02HTG						
Item	Original	INEW	Change or not			
Lead frame	C194	CACS5	Yes			
Die Attach Material	2200D	84-1LMISR4	Yes			
Wire	Gold	Gold	No			
Mold Compound	G600	G600	No			
Plating	PPF	Matte Tin	Yes			

4.0 Packing Method

No change of packing method.

5.0 Physical Differences/Changes:

No change of package dimensions.

6.0 Reliability Test Results Summary:

6.1 **SM24CANB-02HTG summary report**:

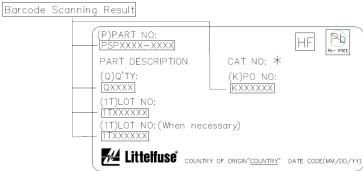
Test Items	Condition	S/S	Results	ETR#
Pre-conditioning (PC)	JESD22-A113	308 each lot	0/924	
DC Blocking (HTRB)	Bias = VRWM, Ta = 150°C, Duration = 1008 Hours	77 each lot	0/231	
Temperature Cycle (TC)	Ta = -55°C to +150°C, Duration = 1000 Cycles	77 each lot	0/231	447000
Temperature/Humidity (H3TRB)	Ta = 85°C, 85% RH, Bias = VRWM, Duration = 1008 Hours	77 each lot	0/231	117689 117690 170510
Autoclave (AC)	Ta = 121°C, 100%RH, 2ATM, Duration = 96 Hours	77 each lot	0/231	170510
Resistance to Solder Heat (RSH)	260°C, 10 sec, M-2031	10 each lot	0/30	
Moisture Sensitivity Level (MSL)	Per Jedec J-STD-020D Level 1	308 each lot	0/924	
Solderability (SD)	ANSI-J-STD-002	10 each lot	0/30	

7.0 Electrical Characteristic Summary:

No change in electrical characteristics. Characterization data is available upon request.

8.0 Changed Part Identification:

Below qualified supplier and it can be identified by code of CAT NO on the label.



9.0 Approvals:

SPA Assistant Product Manager Littelfuse, Wuxi Jordan Hsieh
SPA Product Manager
Littelfuse, HsinChu

Raider Chen
SPA Product Engineer
Littelfuse, HsinChu